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Form PTO-1595 (Rev. 03/01)

04-13-2005

U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/2002)



Tab settings

To the Honorable Commissione

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hed original documents or copy thereof.

1. Name of conveying party(ies):

- 1. Johnson Lien
- 2. Cheng Chun Chung

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address:

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Street Address: No. 8, Li-Hsin Road 6

Science Based Industrial Park

City: Hsin-Chu State: Zip:

Country: Taiwan 300-77 R.O.C.

Additional name(s) & address(es) attached? Yes No

Execution Date: 08/07/2003

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No. (s) 10/637,346

B. Patent No. (s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Murray, Esquire

Internal Address: Duane Morris LLP

Street Address: One Liberty Place

City: Philadelphia State: PA Zip: 19103

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

04-1679

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9. Signature.

Steven E. Koffs, Esquire
Name of Person Signing

Steven E. Koffs
Signature

4-7-05
Date

Total number of pages including cover sheet, attachments, and documents: 6

Mail documents to be recorded with required cover sheet information to:

04/12/2005 MGETACHE 00000048 041679 10637346

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

01 FC:8021 (40.00 DA)

PATENT REEL: 016444 FRAME: 0053

1/9/04

01-09-2004

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U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please return the attached original documents or copy thereof.

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2. Chen Chun Chung

Additional name(s) of conveying party(ies) attached? [] Yes [x] No

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- [x] Assignment [] Merger
[] Security Agreement [] Change of Name
[] Other

Execution Date: 03/07/2003

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Name: Taiwan Semiconductor Manufacturing Co., Ltd.

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Science Based Industrial Park

City: Hsin-Chu State: Zip:

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8. Deposit account number:

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9. Signature.

Joseph A. Powers, Esquire
Name of Person Signing

Joseph A Powers
Signature

01/07/2004
Date

Total number of pages including cover sheet, attachments, and documents: 3

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PATENT REEL: 016444 FRAME: 0054

Serial No. 10/637,346
Filed: 08/08/2003

Express Mail Label No.: EV175965960US

Attorney Docket No.: N1085-00032
[TSMC: 2002-0694]

ASSIGNMENT AND AGREEMENT

For value received, we, **Johnson Lien and Cheng Chun Chung**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **PRESSURE GAUGE MEASURING MULTIPLE PRESSURE VALUES** described in an application for Letters Patent of the United States executed on even date herewith, and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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PATENT
REEL: 016444 FRAME: 0055

Express Mail Label No.: EV175965960US

Attorney Docket No.: N1085-00032
[TSMC: 2002-0694]

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Dated: ✓ 7. Aug. 03

✓ Johnson Lien
Johnson Lien

Residence: ✓
107-1, No. 200, Nioupu E. Rd., Hsinchu city 300, Taiwan (ROC)

Dated: ✓ 7. Aug '03

✓ Cheng Chun Chung
Cheng Chun Chung

Residence: ✓ NO. 63, Duen fong Rd, Hsinchu city 300, Taiwan (ROC)

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